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11/15/02  
Docket No.: M4065.0468/P468 *Mullish*  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Phillip E. Byrd, et al.

Application No.: 09/941,761

Filed: August 30, 2001

For: METHOD AND STRUCTURE FOR  
TEMPORARILY ISOLATING A DIE  
FROM A COMMON CONDUCTOR TO  
FACILITATE WAFER LEVEL TESTING

Group Art Unit: 2812

Examiner: Not Yet Assigned

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT (IDS)

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In accordance with 37 CFR 1.97, Applicant(s) hereby make of record the following additional documents. A PTO Form SB/08 and a full copy of each of these documents accompany this statement.

This statement is not to be interpreted as a representation that the cited documents are material, that an exhaustive search has been conducted, or that no other relevant information exists. Nor shall the citation of any document herein be construed *per se* as a representation that such document is prior art. Moreover, Applicant(s) understand(s) the Examiner will make an independent evaluation of the cited documents.

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits as far as is known to the undersigned.

The Commissioner is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 04-1073, under Order No. M4065.0468/P468. A duplicate copy of this paper is enclosed.

Dated: November <sup>13</sup>/~~12~~, 2002

Respectfully submitted,

By 

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